SCLS251H - OCTOBER 1995 - REVISED JULY 2003

- Operating Range 2-V to 5.5-V V_{CC}
- Latch-Up Performance Exceeds 250 mA Per JESD 17

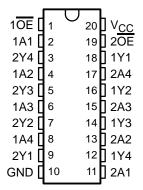
description/ordering information

These octal buffers/drivers are designed specifically to improve the performance and density of 3-state memory-address drivers, clock bus-oriented drivers. and receivers transmitters.

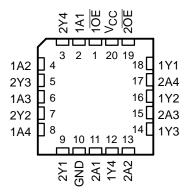
The 'AHC240 devices are organized as two 4-bit buffers/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When OE is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, OE should be tied to VCC through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54AHC240 . . . J OR W PACKAGE SN74AHC240 . . . DB, DGV, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AHC240 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AHC240N	SN74AHC240N
	SOIC - DW	Tube	SN74AHC240DW	AHC240
	3010 - DW	Tape and reel	SN74AHC240DWR	A110240
-40°C to 85°C	SOP – NS	Tape and reel	SN74AHC240NSR	AHC240
40 0 10 03 0	SSOP – DB	Tape and reel	SN74AHC240DBR	HA240
	TSSOP – PW	Tube	SN74AHC240PW	HA240
	1330F - FW	Tape and reel	SN74AHC240PWR	HA240
	TVSOP – DGV	Tape and reel	SN74AHC240DGVR	HA240
	CDIP – J	Tube	SNJ54AHC240J	SNJ54AHC240J
–55°C to 125°C	CFP – W	Tube	SNJ54AHC240W	SNJ54AHC240W
	LCCC – FK	Tube	SNJ54AHC240FK	SNJ54AHC240FK

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



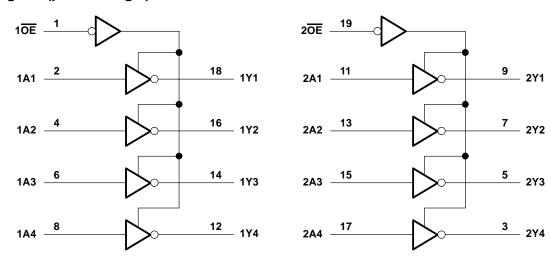
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE (each 4-bit buffer/driver)

INP	UTS	OUTPUT
OE	Α	Y
L	Н	L
L	L	Н
Н	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Output voltage range, VO (see Note 1)		$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}(V_I < 0)$		–20 mA
Output clamp current, IOK (VO < 0 or VO > VC	c)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±25 mA
Continuous current through V _{CC} or GND		±75 mA
Package thermal impedance, θ _{JA} (see Note 2)): DB package	70°C/W
	DGV package	92°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 3)

			SN54A	HC240	SN74A	HC240	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
VIН	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V
		$V_{CC} = 5.5 \text{ V}$	3.85		3.85		
		V _{CC} = 2 V		0.5		0.5	
VIL	Low-level input voltage	V _{CC} = 3 V		0.9		0.9	V
		V _{CC} = 5.5 V		1.65		1.65	
٧ı	Input voltage		0	5.5	0	5.5	V
٧o	Output voltage		0	Vcc	0	VCC	V
		V _{CC} = 2 V		-50		-50	μΑ
IOH	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4		-4	mA
		$V_{CC} = 5 V \pm 0.5 V$		-8		-8	IIIA
		V _{CC} = 2 V		50		50	μΑ
loL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4		4	mA
		$V_{CC} = 5 V \pm 0.5 V$		8		8	IIIA
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100		100	ns/V
Δι/ΔV	Input transition rise or fall rate $V_{CC} = 5 \text{ V} \pm 0.$			20		20	115/ V
T _A	Operating free-air temperature	-	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	V	T,	ղ = 25°C	;	SN54A	HC240	SN74AI	HC240	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V	1.9	2		1.9		1.9		
	I _{OH} = -50 μA	3 V	2.9	3		2.9		2.9		
Voн		4.5 V	4.4	4.5		4.4		4.4		V
	I _{OH} = -4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8		3.8		
		2 V			0.1		0.1		0.1	
	I _{OL} = 50 μA	3 V			0.1		0.1		0.1	
V _{OL}		4.5 V			0.1		0.1		0.1	V
	I _{OL} = 4 mA	3 V			0.36		0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
lį	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	μΑ
loz†	$V_O = V_{CC}$ or GND, $V_I (\overline{OE}) = V_{IL}$ or V_{IH}	5.5 V			±0.25		±2.5		±2.5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40		40	μΑ
C _i	$V_I = V_{CC}$ or GND	5 V		2.5	10				10	pF
Co	$V_O = V_{CC}$ or GND	5 V		3.5					·	pF

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 \text{ V}$.

[†] The parameter IOZ includes the input leakage current.



SN54AHC240, SN74AHC240 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	λ = 25°C	;	SN54A	HC240	SN74AI	HC240	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
^t PLH	А	Y	C _I = 15 pF		5.3*	7.5*	1*	9*	1	9	ns
t _{PHL}	Α	'	C[= 15 pi		5.3*	7.5*	1*	9*	1	9	115
^t PZH	ŌĒ	Y	C _I = 15 pF		6.6*	10.6*	1*	12.5*	1	12.5	ns
^t PZL	OE	ī	CL = 15 pr		6.6*	10.6*	1*	12.5*	1	12.5	115
^t PHZ	ŌĒ	Y	C _L = 15 pF		7.8*	11.5*	1*	12.5*	1	12.5	ns
tPLZ	OE	Ť	CL = 13 pr		7.8*	11.5*	1*	12.5*	1	12.5	115
^t PLH	Α	Y	C ₁ = 50 pF		7.8	11	1	12.5	1	12.5	ns
^t PHL	Λ	'	CL = 50 pr		7.8	11	1	12.5	1	12.5	115
^t PZH	ŌĒ	Y	C _I = 50 pF		9.1	14.1	1	16	1	16	ns
^t PZL	OE	ī	CL = 50 pr		9.1	14.1	1	16	1	16	115
^t PHZ	ŌĒ	Y	C: - 50 pE		10.3	14	1	16	1	16	nc
tPLZ	OE	ī	C _L = 50 pF		10.3	14	1	16	1	16	ns
tsk(o)			C _L = 50 pF			1.5**				1.5	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	չ = 25°C	;	SN54A	HC240	SN74A	HC240	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	Α	Y	C _I = 15 pF		3.6*	5.5*	1*	6.5*	1	6.5	ns
^t PHL	Α	'	CL = 13 pr		3.6*	5.5*	1*	6.5*	1	6.5	115
^t PZH	ŌĒ	Y	C _I = 15 pF		4.7*	7.3*	1*	8.5*	1	8.5	ns
^t PZL	OE	'	CL = 13 pr		4.7*	7.3*	1*	8.5*	1	8.5	115
^t PHZ	ŌĒ	Y	C _I = 15 pF		5.2*	7.2*	1*	8.5*	1	8.5	ns
t _{PLZ}	OE	ī	OL = 13 pr		5.2*	7.2*	1*	8.5*	1	8.5	110
^t PLH	Α	Y	C ₁ = 50 pF		5.1	7.5	1	8.5	1	8.5	ns
^t PHL	Λ	'	CL = 30 pr		5.1	7.5	1	8.5	1	8.5	115
^t PZH	ŌĒ	Y	C _I = 50 pF		6.2	9.3	1	10.5	1	10.5	ns
^t PZL	OE	'	CL = 30 pr		6.2	9.3	1	10.5	1	10.5	115
^t PHZ	ŌĒ	Y	C 50 pE		6.7	9.2	1	10.5	1	10.5	nc
t _{PLZ}	OE	ſ	C _L = 50 pF		6.7	9.2	1	10.5	1	10.5	ns
^t sk(o)			C _L = 50 pF			1**				1	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



^{**} On products compliant to MIL-PRF-38535, this parameter does not apply.

^{**} On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

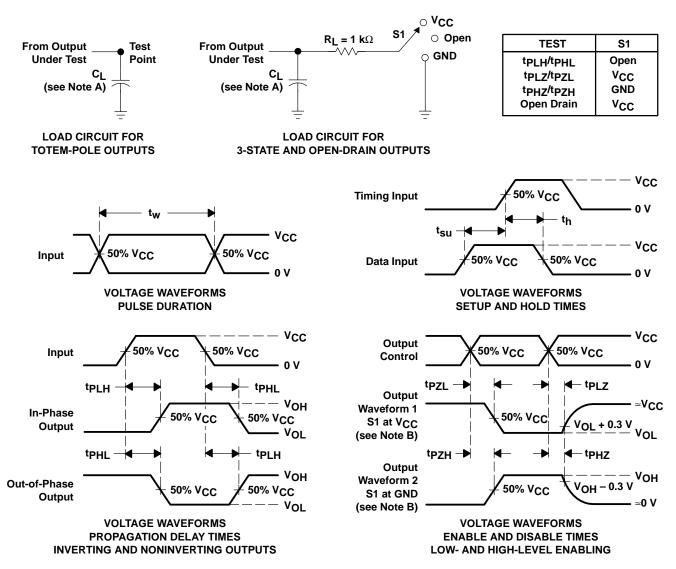
	PARAMETER	SN7	SN74AHC240				
	PARAMETER	MIN	TYP	MAX	UNIT		
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.6		V		
V _{OL} (V)	Quiet output, minimum dynamic V _{OL}		-0.6		V		
VOH(V)	Quiet output, minimum dynamic VOH		4.6		V		
VIH(D)	High-level dynamic input voltage	3.5			V		
V _{IL(D)}	Low-level dynamic input voltage			1.5	V		

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST C	SNOITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	10	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9680701Q2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9680701Q2A SNJ54AHC 240FK	Samples
5962-9680701QRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9680701QR A SNJ54AHC240J	Samples
5962-9680701QSA	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9680701QS A SNJ54AHC240W	Samples
SN74AHC240DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC240	Samples
SN74AHC240DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC240	Samples
SN74AHC240N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHC240N	Samples
SN74AHC240NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC240	Samples
SN74AHC240PW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA240	Samples
SN74AHC240PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA240	Samples
SN74AHC240PWRE4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA240	Samples
SNJ54AHC240FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9680701Q2A SNJ54AHC 240FK	Samples
SNJ54AHC240J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9680701QR A SNJ54AHC240J	Samples
SNJ54AHC240W	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9680701QS A SNJ54AHC240W	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

PACKAGE OPTION ADDENDUM

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LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54AHC240, SN74AHC240:

Catalog: SN74AHC240

Military: SN54AHC240

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

PACKAGE OPTION ADDENDUM

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• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC240DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AHC240NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AHC240PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

7 III GITTIOTOTOTO GITO TIOTITITICA							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC240DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AHC240NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AHC240PWR	TSSOP	PW	20	2000	853.0	449.0	35.0

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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